

#2872

AMENDMENT TRANSMITTAL LETTER (Large Entity)		Docket No. BUR919990120US2(13344A)
Applicant(s): Chung H. Lam		

Serial No. 10/029,512	Filing Date December 21, 2001	Examiner Ron E. Pompey	Group Art Unit 2812
---------------------------------	---	----------------------------------	-------------------------------

Invention: **PROCESS USING POLY-BUFFERED STI**

RECEIVED
JAN 30 2003
IC 2800 MAIL ROOM

TO THE ASSISTANT COMMISSIONER FOR PATENTS:

Transmitted herewith is an amendment in the above-identified application.
The fee has been calculated and is transmitted as shown below.

CLAIMS AS AMENDED					
	CLAIMS REMAINING AFTER AMENDMENT	HIGHEST # PREV. PAID FOR	NUMBER EXTRA CLAIMS PRESENT	RATE	ADDITIONAL FEE
TOTAL CLAIMS	6 -	20 =	0 x	\$18.00	\$0.00
INDEP. CLAIMS	4 -	3 =	1 x	\$84.00	\$84.00
Multiple Dependent Claims (check if applicable) <input type="checkbox"/>					\$0.00
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT					\$84.00

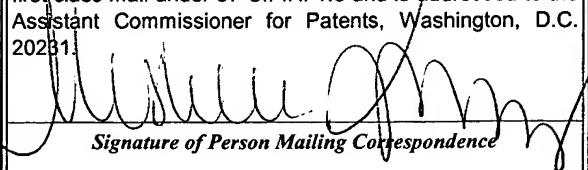
- ☒ No additional fee is required for amendment.
- ☐ Please charge Deposit Account No. _____ in the amount of _____
A duplicate copy of this sheet is enclosed.
- ☐ A check in the amount of _____ to cover the filing fee is enclosed.
- ☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. **09-0456/IBM**
A duplicate copy of this sheet is enclosed.
 - ☒ Any additional filing fees required under 37 C.F.R. 1.16.
 - ☒ Any patent application processing fees under 37 CFR 1.17.


Signature

Dated: **January 24, 2003**

Leslie S. Szivos
Registration No. 39,394

SCULLY, SCOTT, MURPHY & PRESSER
400 Garden City Plaza
Garden City, New York 11530
(516) 742-4343

I certify that this document and fee is being deposited on 1/23/03 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.
 Signature of Person Mailing Correspondence
Mishelle Mustafa Typed or Printed Name of Person Mailing Correspondence

CC:



#6/Am
B
1/31/03
V/S
PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Chung H. Lam

Examiner: Ron E. Pompey

Serial No: 10/029,512

Art Unit: 2812

Filed: December 21, 2001

Docket: BUR919990120US2 (13344A)

For: PROCESS USING POLY-BUFFERED STI

Dated: January 24, 2003

Assistant Commissioner for Patents
United States Patent and Trademark Office
Washington, D.C. 20231

RECEIVED
JAN 30 2003
TC 2800 MAIL ROOM

AMENDMENT AND RESPONSE

Sir:

In response to the Office Action dated October 24, 2002, applicants submit the following amendments and remarks for entry of record in the above-identified patent application.

01/28/2003 SZENDIE1 00000103 090456 10029512

01 FC:1201 84.00 CH

IN THE SPECIFICATION:

Please amend Page 12, lines 1-15, as follows:

b
--Next, as shown in Fig. 2E, the structure thus formed is planarized down to the surface of the substrate utilizing a conventional planarization process such as chemical-mechanical

CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner of Patents and Trademarks, Washington, D.C. 20231 on *January 24, 2003*

Dated: January 24, 2003

Mishelle Mustafa
Mishelle Mustafa